

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSIII)

# 2SK2607

Chopper Regulator, DC-DC Converter and Moter Drive Applications

Unit: mm

- Low drain-source ON resistance :  $R_{DS(ON)} = 1.0 \Omega$  (typ.)
- High forward transfer admittance :  $|Y_{fs}| = 7.0 \text{ S}$  (typ.)
- Low leakage current :  $I_{DSS} = 100 \mu\text{A}$  (max) ( $V_{DS} = 640 \text{ V}$ )
- Enhancement mode :  $V_{th} = 2.0 \sim 4.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

## Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

| Characteristics                                      |                | Symbol    | Rating         | Unit             |
|--|----------------|-----------|----------------|------------------|
| Drain-source voltage                                 |                | $V_{DSS}$ | 800            | V                |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                | $V_{DGR}$ | 800            | V                |
| Gate-source voltage                                  |                | $V_{GSS}$ | $\pm 30$       | V                |
| Drain current  | DC (Note 1)    | $I_D$     | 9              | A                |
|  | Pulse (Note 1) | $I_{DP}$  | 27             |                  |
| Drain power dissipation ( $T_c = 25^\circ\text{C}$ ) |                | $P_D$     | 150            | W                |
| Single pulse avalanche energy (Note 2)               |                | $E_{AS}$  | 778            | mJ               |
| Avalanche current                                    |                | $I_{AR}$  | 9              | A                |
| Repetitive avalanche energy (Note 3)                 |                | $E_{AR}$  | 15             | mJ               |
| Channel temperature                                  |                | $T_{ch}$  | 150            | $^\circ\text{C}$ |
| Storage temperature range                            |                | $T_{stg}$ | $-55 \sim 150$ | $^\circ\text{C}$ |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## Thermal Characteristics

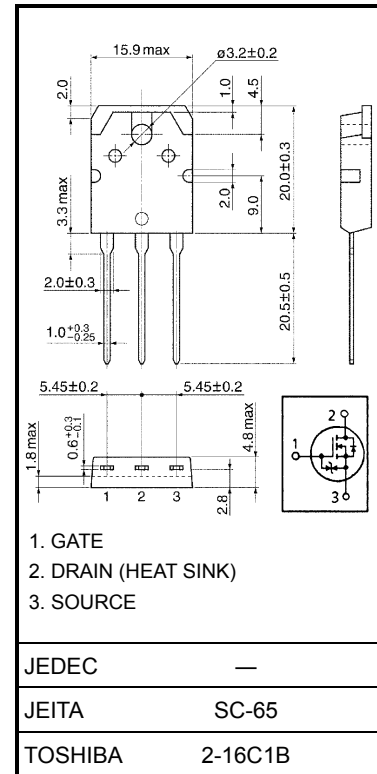
| Characteristic                         | Symbol         | Max   | Unit                        |
|--|----------------|-------|-----------------------------|
| Thermal resistance, channel to case    | $R_{th(ch-c)}$ | 0.883 | $^\circ\text{C} / \text{W}$ |
| Thermal resistance, channel to ambient | $R_{th(ch-a)}$ | 50    | $^\circ\text{C} / \text{W}$ |

Note 1: Ensure that the channel temperature does not exceed  $150^\circ\text{C}$ .

Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 17.4 \text{ mH}$ ,  $R_G = 25 \Omega$ ,  $I_{AR} = 9 \text{ A}$

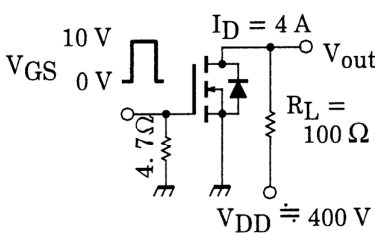
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.  
Please handle with caution.



Weight: 4.6 g (typ.)

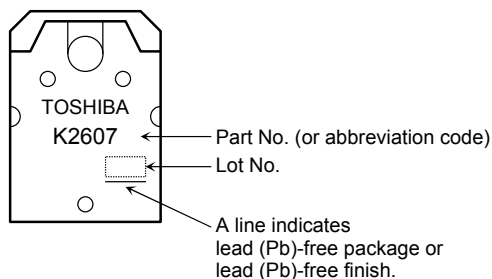
## Electrical Characteristics (Ta = 25°C)

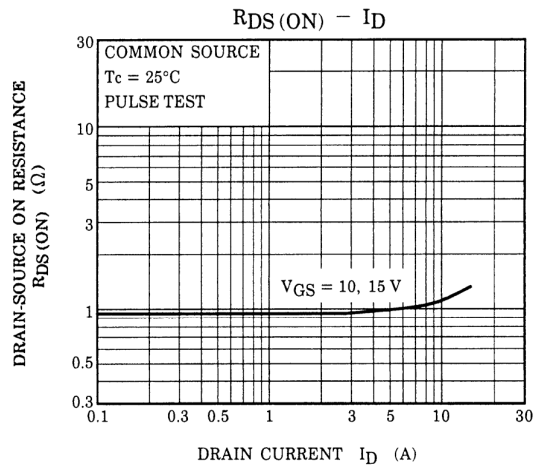
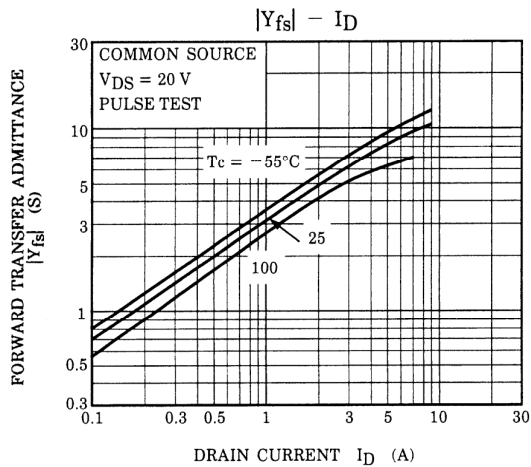
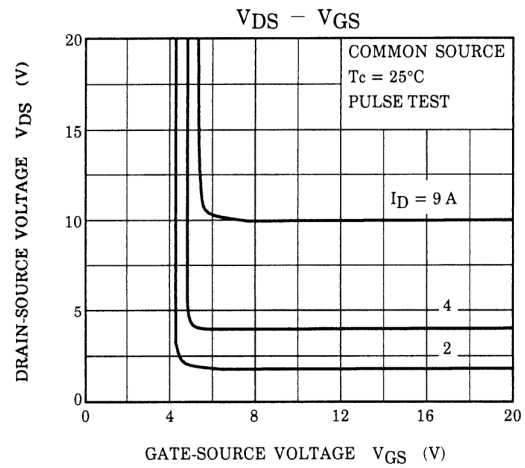
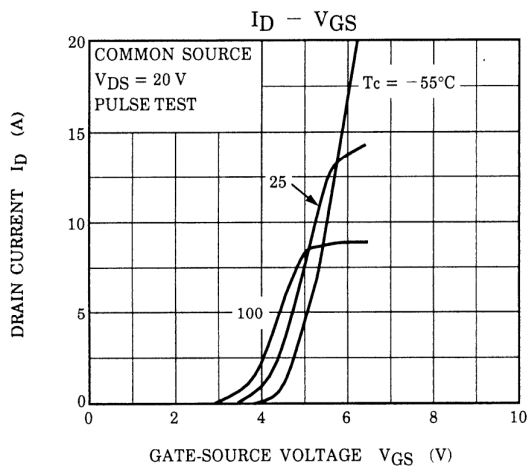
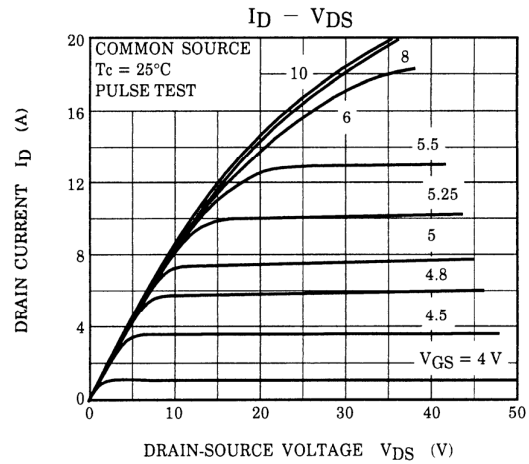
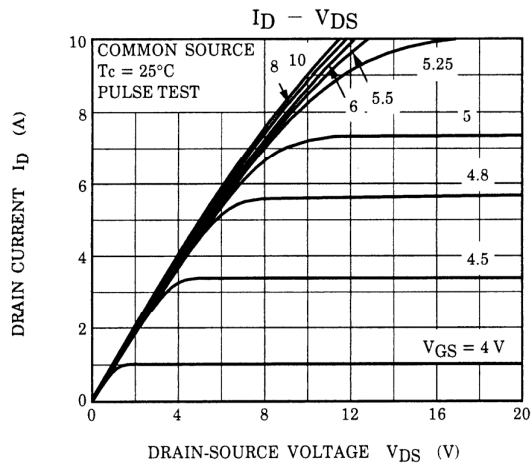
| Characteristics                                 |               | Symbol         | Test Condition   | Min      | Typ. | Max      | Unit          |
|---|---------------|----------------|--|----------|------|----------|---------------|
| Gate leakage current                            |               | $I_{GSS}$      | $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$  | —        | —    | $\pm 10$ | $\mu\text{A}$ |
| Gate-source breakdown voltage                   |               | $V_{(BR) GSS}$ | $I_G = \pm 10 \mu\text{A}, V_{DS} = 0 \text{ V}$   | $\pm 30$ | —    | —        | V             |
| Drain cut-off current                           |               | $I_{DSS}$      | $V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}$   | —        | —    | 100      | $\mu\text{A}$ |
| Drain-source breakdown voltage                  |               | $V_{(BR) DSS}$ | $I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$  | 800      | —    | —        | V             |
| Gate threshold voltage                          |               | $V_{th}$       | $V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$  | 2.0      | —    | 4.0      | V             |
| Drain-source ON resistance                      |               | $R_{DS(ON)}$   | $V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$   | —        | 1.0  | 1.2      | $\Omega$      |
| Forward transfer admittance                     |               | $ Y_{fs} $     | $V_{DS} = 15 \text{ V}, I_D = 4 \text{ A}$   | 3.0      | 7.0  | —        | S             |
| Input capacitance                               |               | $C_{iss}$      | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$   | —        | 2160 | —        | pF            |
| Reverse transfer capacitance                    |               | $C_{rss}$      |  | —        | 45   | —        |               |
| Output capacitance                              |               | $C_{oss}$      |  | —        | 200  | —        |               |
| Switching time                                  | Rise time     | $t_r$          |  <p><math>I_D = 4 \text{ A}</math><br/><math>R_L = 100 \Omega</math><br/><math>V_{DD} \approx 400 \text{ V}</math><br/>Duty <math>\leq 1\%</math>, <math>t_w = 10 \mu\text{s}</math></p> | —        | 25   | —        | ns            |
|   | Turn-on time  | $t_{on}$       |  | —        | 60   | —        |               |
|   | Fall time     | $t_f$          |  | —        | 25   | —        |               |
|   | Turn-off time | $t_{off}$      |  | —        | 110  | —        |               |
| Total gate charge (gate-source plus gate-drain) |               | $Q_g$          | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$   | —        | 68   | —        | nC            |
| Gate-source charge                              |               | $Q_{gs}$       |  | —        | 38   | —        |               |
| Gate-drain ("miller") Charge                    |               | $Q_{gd}$       |  | —        | 30   | —        |               |

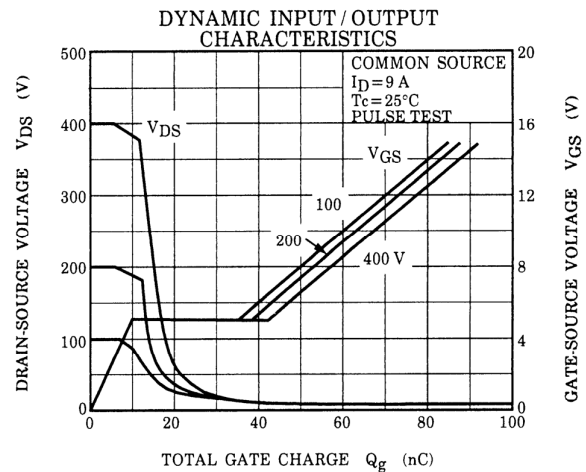
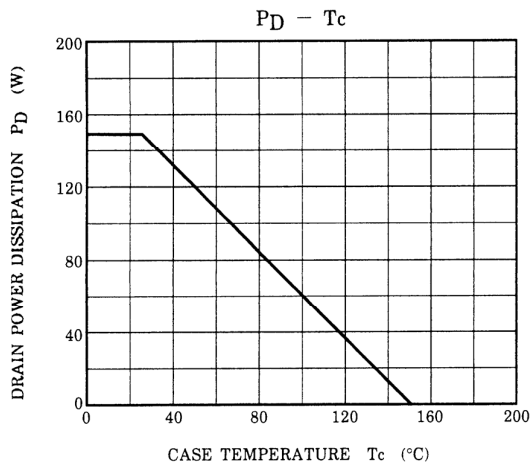
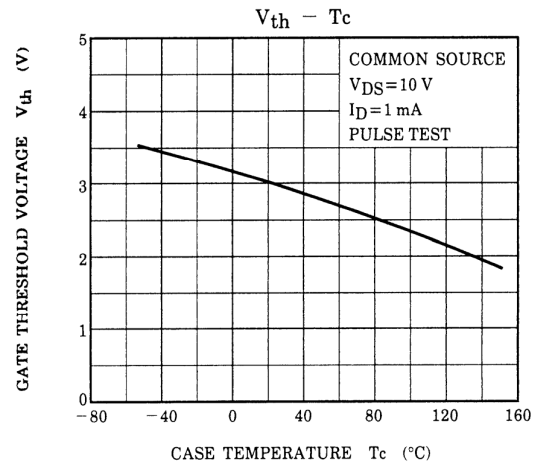
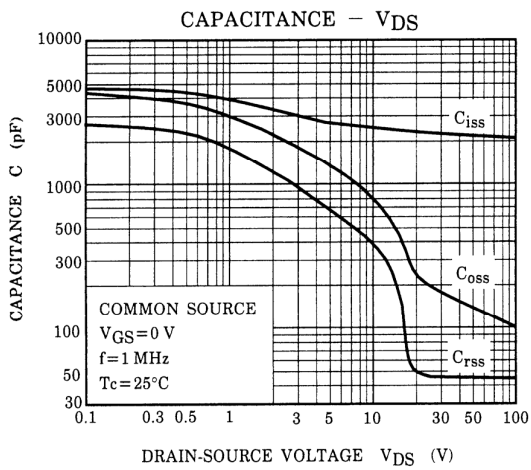
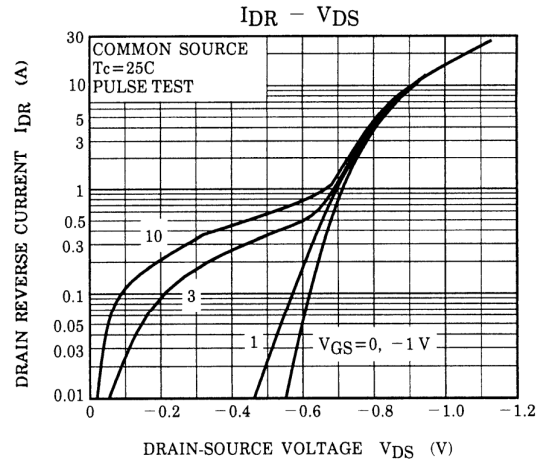
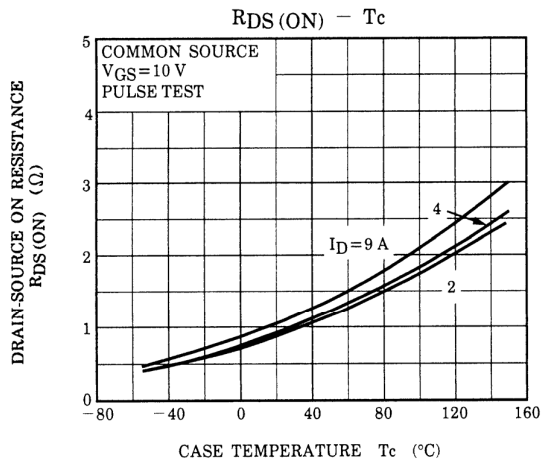
## Source-Drain Ratings and Characteristics (Ta = 25°C)

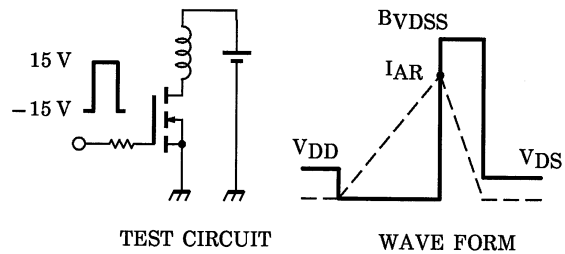
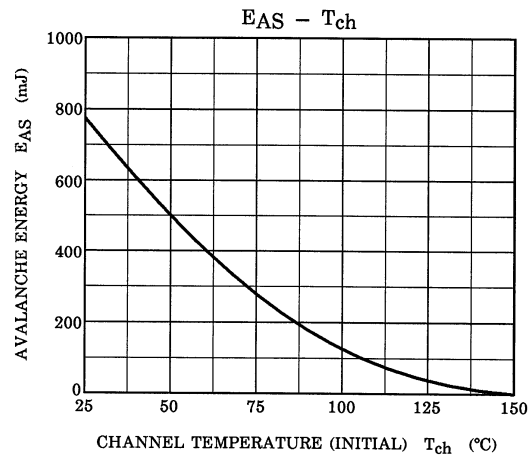
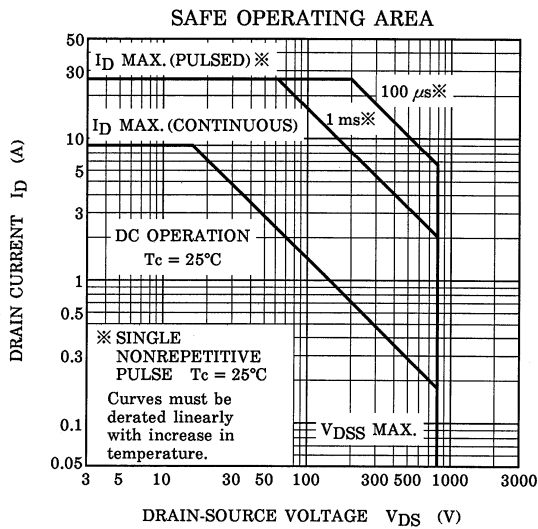
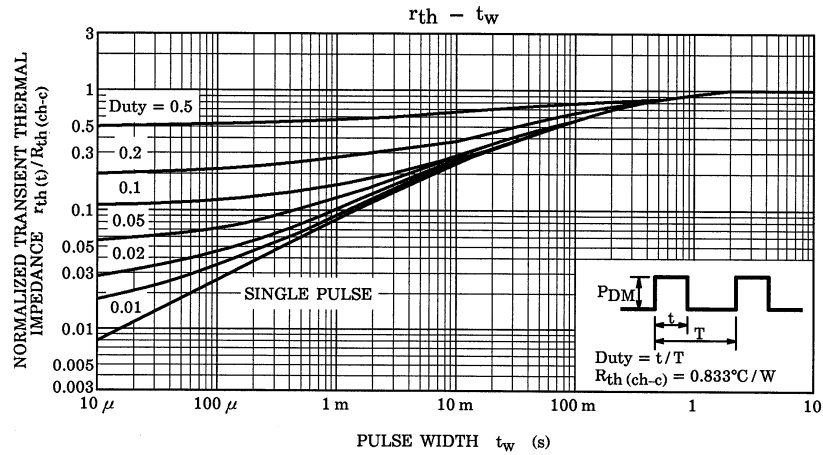
| Characteristics                           | Symbol    | Test Condition   | Min | Typ. | Max  | Unit          |
|---|-----------|--|-----|------|------|---------------|
| Continuous drain reverse current (Note 1) | $I_{DR}$  | —  | —   | —    | 9    | A             |
| Pulse drain reverse current (Note 1)      | $I_{DRP}$ | —  | —   | —    | 27   | A             |
| Forward voltage (diode)                   | $V_{DSF}$ | $I_{DR} = 9 \text{ A}, V_{GS} = 0 \text{ V}$   | —   | —    | -1.9 | V             |
| Reverse recovery time                     | $t_{rr}$  | $I_{DR} = 9 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 100 \text{ A} / \mu\text{s}$ | —   | 1000 | —    | ns            |
| Reverse recovery charge                   | $Q_{rr}$  |  | —   | 12   | —    | $\mu\text{C}$ |

## Marking









$$R_G = 25 \, \Omega \quad V_{DD} = 90 \, \text{V}, L = 17.4 \, \text{mH} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDS}}{B_{VDS} - V_{DD}} \right)$$

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20070701-EN

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